

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Nov. 19, 2012

Expected First Date Code of Changed Product :1247

Description of Change (From) :
6 inch wafer diameter for the detector die component.

Description of Change (To) :
8 inch wafer diameter for the detector die component.

Reason for Change:
Fairchild Semiconductor is closing the 6" fabrication line in Maine USA and qualifying a 8" fabrication line at the same location. This is to increase the production capacity in our wafer fabrication facilities in USA. This PCN complements the product list in PCN P229A issued on 23rd March 2012.

Affected Product(s):

FOD2741A	FOD2741B	FOD2742B
FOD2743B	MOC205M	MOC207M
MOC217M	MOC217R2M	MOC217R2VM
MOC217VM	MOCD207M	MOCD217M
MOCD217R2M	MOCD217R2VM	MOCD217VM

Qualification Plan	Device	Package	Process	No. of Lots
Q20110520	FOD3120	8PW	N/A	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/693
Bond Pull		JESD22-C100		0/120
Bond Shear		AEC-Q100-001		0/120
Die Shear		MIL-STD-883-2019		0/120
High Temperature Op Life Test	100C		1000 hrs	0/231
High Temperature Storage Life	125C	JESD22-A103	1000 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	1000 hrs	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20100529	H11L1M	6PW	N/A	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/1124
Bond Pull		JESD22-C100		0/120
Bond Shear		AEC-Q100-001		0/120
Die Shear		MIL-STD-883-2019		0/120
High Temperature Op Life Test	100C		1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
High Temperature Reverse Bias	100C		1000 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	1000 hrs	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20100602	CNY173M	6PW	N/A	3

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/1124
Bond Pull		JESD22-C100		0/120
Bond Shear		AEC-Q100-001		0/120
Die Shear		MIL-STD-883-2019		0/120
High Temperature Op Life Test	100C		1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	1000 hrs	0/231